



ANALOG DEVICES INC

12-Bit, 10 MSPS A/D Converter

AD9005A

1.1 Scope.

This specification covers the requirements for a 12-bit, high speed analog-to-digital converter (ADC). The AD9005A is a complete 12-bit ADC which includes on-board track-and-hold amplifier, voltage reference, and timing circuits.

1.2 Part Number.

The complete part number is as follows:

Device	Part Number
-1	AD9005ATM/883B

1.2.3 Case Outline.

See Appendix 1 of General Specification ADI-M-1000: package outline:

(X)	Package	Description
M	M-46	46-Pin Hermetic Metal DIP

1.3 Absolute Maximum Ratings. ($T_A = +25^\circ\text{C}$ unless otherwise noted)

Power Supply Voltages ($\pm V_S$)	$\pm 6\text{ V}$
Positive Supply Voltage ($+V_{CC}$)	$+18\text{ V}$
Negative Supply Voltage ($-V_{EE}$)	-18 V
Power Dissipation (Typical)	260 mW
Analog Input Voltage (Pin 45)	$\pm 3.0\text{ V dc}$
Digital Input Voltage	$-0.5\text{ V to } +V_S$
Digital Output Current	4 mA
Junction Temperature	$+175^\circ\text{C}$
Operating Temperature Range (Case)	$-55^\circ\text{C to } +125^\circ\text{C}$
Storage Temperature Range (Case)	$-65^\circ\text{C to } +150^\circ\text{C}$
Lead Temperature (Soldering 10 sec)	$+300^\circ\text{C}$

1.5 Thermal Characteristics.

Maximum junction temperature should not be allowed to exceed $+175^\circ\text{C}$. Hybrid thermal model:

$$T_{\text{JUNCTION}} = T_{\text{AMBIENT}} + P_{\text{DISSIPATION}} \times (\theta_{\text{CA}}) + (T_{\text{S}} - T_{\text{C}})_{\text{max}}$$

where $(T_{\text{S}} - T_{\text{C}})_{\text{max}} = 10^\circ\text{C}$. $\theta_{\text{CA}} = 14^\circ\text{C/W}$ in still air; $\theta_{\text{CA}} = 6^\circ\text{C/W}$ with 500 LFPM air flow.

AD9005A—SPECIFICATIONS

0816800 0040590 326 ANA

Table 1.

Test	Symbol	Device	Design Limits ¹	Sub Group 1	Sub Group 2, 3	Sub Group 4	Sub Group 5, 6	Test Condition ²	Units
Differential Nonlinearity	DNL	-1				±0.75	-1.0 +1.5		LSB
Integral Nonlinearity ³	INL	-1	±2.25						LSB
Gain Error		-1				±1.0	±2.0		% FS
Offset Error	V _{OS}	-1				±15	±40		mV
Input Resistance	R _I	-1		950	950				Ω min
				1050	1050				Ω max
Maximum Conversion Rate		-1				10.1	10.1		MSPS min
Aperture Uncertainty (Jitter)	t _j	-1	20					@ +25°C	ps rms
Transient Response	t _{TR}	-1	120					FS Step Input to ±1 LSB @ +25°C	ns
Overvoltage Recovery Time	t _{OR}	-1	250					200% Input to ±1 LSB @ +25°C	ns
Harmonic Distortion ⁴	HD	-1					-63	f _{IN} = 4.3 MHz	dBc min
Signal-to-Noise Ratio ⁵	SNR	-1					60	f _{IN} = 4.3 MHz	dB min
Encode Pulse Voltage (HIGH)	V _{E(H)}	-1	2.0						V min
Encode Pulse Voltage (LOW)	V _{E(L)}	-1	0.8						V max
Encode Pulse Current (HIGH)	I _{E(H)}	-1		150	150				μA max
Encode Pulse Current (LOW)	I _{E(L)}	-1		150	150				μA max
Encode Pulse Width (HIGH)	t _{E(H)}	-1	25					@ +25°C	ns min
High Level Output Voltage	V _{OH}	-1		2.4	2.4			2 mA source	V min
Low Level Output Voltage	V _{OL}	-1		0.4	0.4			4 mA sink	V max
Positive Analog Supply Current (+5.0 V)	+I _{AS}	-1		210	210				mA max
Negative Analog Supply Current (-5.2 V)	-I _{AS}	-1		250	250				mA max
Positive Digital Supply Current (-5.2 V)	+I _{DS}	-1		60	60				mA max
Negative Digital Supply Current (-5.2 V)	-I _{DS}	-1		100	100				mA max
Positive Supply Current (+15.0 V)	+I _{CC}	-1		25	25				mA max
Negative Supply Current (-15.0 V)	-I _{EE}	-1		55	55				mA max
Power Supply Rejection Ratio ⁶	PSRR	-1				0.02			%/ % max
Power Dissipation	P _{DISS}	-1		4.1					W max

NOTES

¹Indicates specification which is guaranteed but not tested. Value shown is at T_A = full unless otherwise noted in Test Conditions.

²+V_{CC} = +15 V; -V_{EE} = -15 V; +V_S = +5 V; -V_S = -5.2 V, unless otherwise indicated.

³Parameter is tested at +25°C; guaranteed but not tested at temperature extremes.

⁴Input at 1 dB below full scale; worst case spurious in-band signal relative to input level.

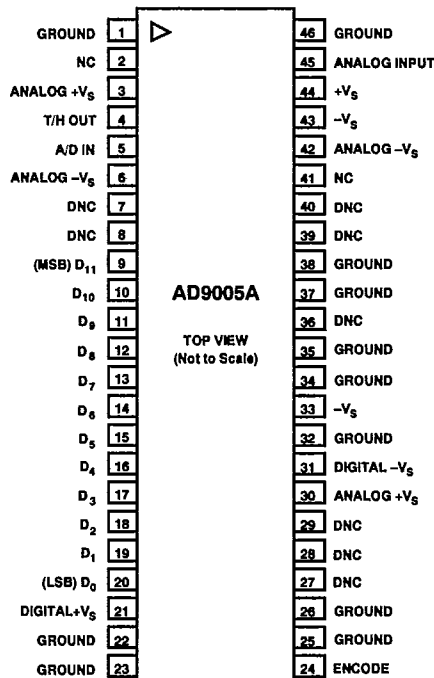
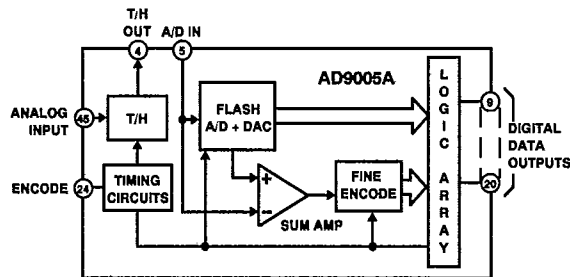
⁵Input at 1 dB below full scale; rms signal to rms noise, including harmonics.

⁶Sensitivity of full-scale gain error with respect to power supply variation with supply min/max limits; PSRR is tested over given voltage range.

ANALOG DEVICES INC

65E D

3.2.1 Functional Block Diagram and Terminal Assignments.



NC = NO CONNECT
DNC = DO NOT CONNECT

3.2.4 Microcircuit Technology Group.

This microcircuit is covered by technology group (I).

4.2.1 Life Test/Burn-In Circuit.

Steady state life test is per MIL-STD-883 Method 1005. Burn-in is per MIL-STD-883 Method 1015 test condition (B).

